



Document Title: Product Screen Flow	Document Number: PD00004
Description: Monolithic Product Flow Matrix	Doc: Process Doc

Confidential

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Monolithic Devices-Product Flow Matrix

The device shall be screened as specified in the table below. NON-COMPLIANT but in accordance with Mil-Std-883. Manufactured batches shall have Lots tests carried out in accordance with Mil-Std-883 (Mil-M-38510) All manufacturing is carried out at DSCC approved facilities.

Screening	Method	/C	/I	/B (5004)	/B05 (5005)	QA test condition	UpScreen only
Visual Inspection Kit	Incoming and Outgoing Inspection Procedures	100%	100%	100%	100%		100%
Temperature Cycling				100%	100%	1010, test condition C	-
Centrifuge					100%	2001E	-
Constant acceleration				100%	100%	2001, test condition E (min)Y1 orientation	-
Seal a. Fine b. Gross			100%	100%	100%	1014 Cond A or B Cond C	-
Visual inspection				100%	100%	FT WIP documentation	100%
Interim (pre-BI)Electrical	In accordance with applicable device specification. or as defined in QM p4.1.1			100%	100%		100%
Burn-in test	Dynamic			100%	100%	1015, 160 hours at 125°C minimum	-
Percentage defective allowable (PDA) calculation	Review			5%	QCI		-
Final GrpA Electrical Tests A)Static Tests: 25oC (subgrp.1) Max.& Min. subgrp 2,3) B) Dynamic (Linear devices) 25oC (subgrp.4) Max.& Min. subgrp 5,6) C)Functional 25oC (subgrp.7) Max.& Min. subgrp 8) D) Switching (Digital devices) 25oC (subgrp.9) Max.& Min. subgrp 10,11)	In accordance with applicable device specification. or as defined in QM p4.1.1	100%	100% -40oC +85oC	100% -55oC +125oC	100% -55oC +125oC	5005 p2	100% Tmin Tmax
External Visual			100%	100%	100%	2009	100%
Group B				-	100%	2015/2003/2011	-
Group C				-	100%	1005	-
Group D				-	100%	2016/2004/1014/1011/ 1010/1004/2002/2007/ 2001/1009/1018/2025/2024	-
Marking & Inspect	As FT WIP documentation	100%		100%	100%		100%
Data Preparation	As FT QA documentation	100%		100%	100%		100%
Dry Bake store/ship	As FT WIP documentation	100%		100%	100%	JEDEC	100%

Note.
Suffix code

- /C = Parts are assembled and tested to Commercial temperature 0oC to +70oC
- /I = Parts are assembled and tested to Extended temperature -40oC to +85oC
- /B = Parts are Based on METHOD 5004 screening procedures and Mil-Std-883F Test methods.
- /B5 = Parts are Based on Control Procedures for :
GroupA (Electrical)
GroupB (Enviromental)
GroupC (Die related)
GroupD (Package related) Tests.
It is based on METHOD 5005 Conformance procedures and Mil-Std-883F Test methods

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Issue:	Date:	Approval:	Dept:
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